

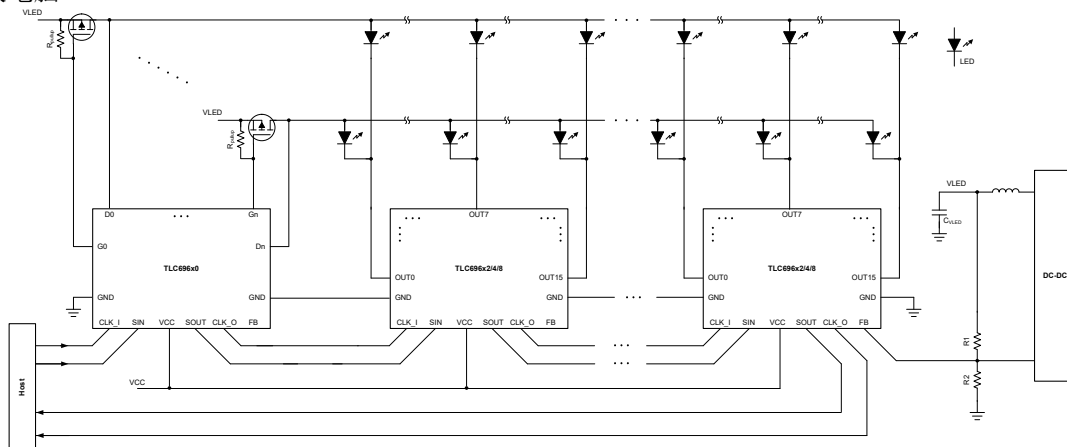
TLC696x0 TLC696x2/4/8 扫描 MOSFET 控制器

1 特性

- 工作电压 V_{CC} 范围：3V 至 5.5V
- 灵活的 P-MOSFET 驱动选项：
 - 最大驱动电流/维持电压：
 - 30mA/20V：TLC69600
 - 60mA/20V：TLC69610
 - 30mA/50V：TLC69650
 - 60mA/50V：TLC69660
 - 全局 8 位最大电流 (MC) 设置
 - 单独 8 位通道电流 (CC) 设置
- 高速菊花链接口：
 - I/O 电压兼容：1.8 V/3.3 V
 - 数据传输速率：高达 20MHz
- EMI 增强：
 - 可编程接口驱动能力
- 显示质量改进：
 - 超低亮度更新延迟
 - 可编程插黑
 - 无闪烁的可变刷新率 (VRR)
- 诊断：
 - 器件热关断检测
 - 报告界面选项：
 - UART 和中断引脚 (INT)
 - 两线制输出：CLK_O 和 SOUT

2 应用

- LCD 局部调光背光：
 - 电视
 - 监视器
 - 笔记本电脑
 - 平板电脑



简化原理图

3 说明

TLC696x0 是一款与电流阱驱动器 TLC696x2/4/8 兼容的扫描 MOSFET 控制器，可实现 2/4/8 时分多路复用控制。每个器件都集成了 16 个恒定电流阱，可用于多达 8 个扫描 MOSFET 控制。该器件具有重影消除功能，可消除上部重影。

为了优化系统效率，该器件配备了自适应余量电压控制方案，以直接控制直流/直流。为了简化系统布局，只需将串行链中最后一个器件的 FB 引脚连接到直流/直流。该器件还集成了超低亮度更新延迟、插黑和 VRR 特性，以提高显示质量。

TLC696x0 有三个错误标志：用于诊断的 LED 开路检测 (LOD)、LED 短路检测 (LSD) 和热关断检测 (TSD)。该器件实现了两个回读选项 (包括 UART/INT 和 SOUT/CLK_O)，可通过寄存器进行编程。

器件信息

器件型号	封装 ⁽¹⁾	封装尺寸 (标称值)
TLC696x0	DSBGA (24)	1.58 mm × 2.43 mm
	WQFN (24)	4mm × 4mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

DATE	REVISION	NOTES
April 2023	*	Initial Release

5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

5.1 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

5.2 支持资源

[TI E2E™ 支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

5.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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5.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

5.5 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC69600RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69600	Samples
TLC69600YBHR	ACTIVE	DSBGA	YBH	24	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	TLC69600	Samples
TLC69610RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69610	Samples
TLC69650RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69650	Samples
TLC69660RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	69660	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

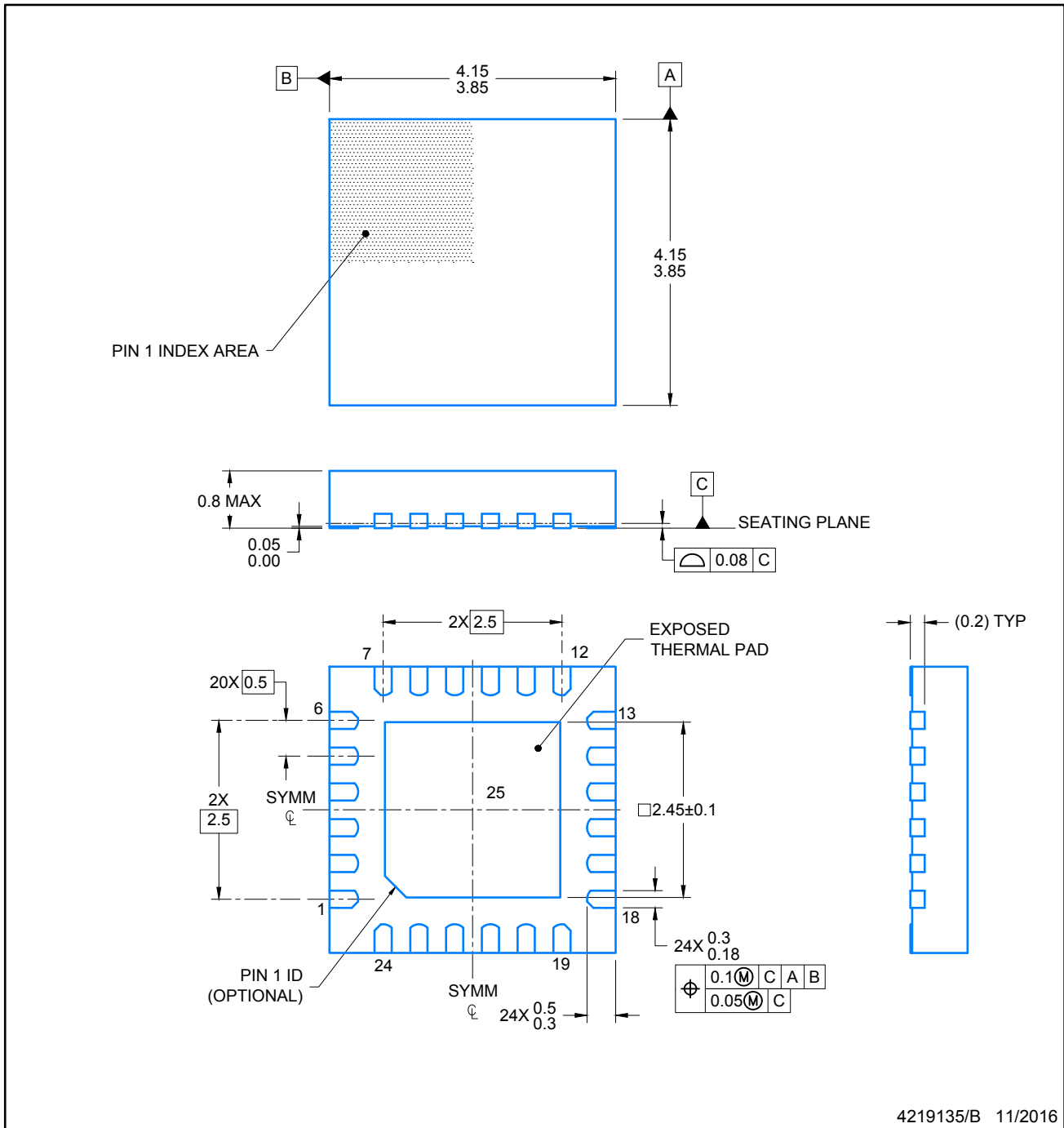
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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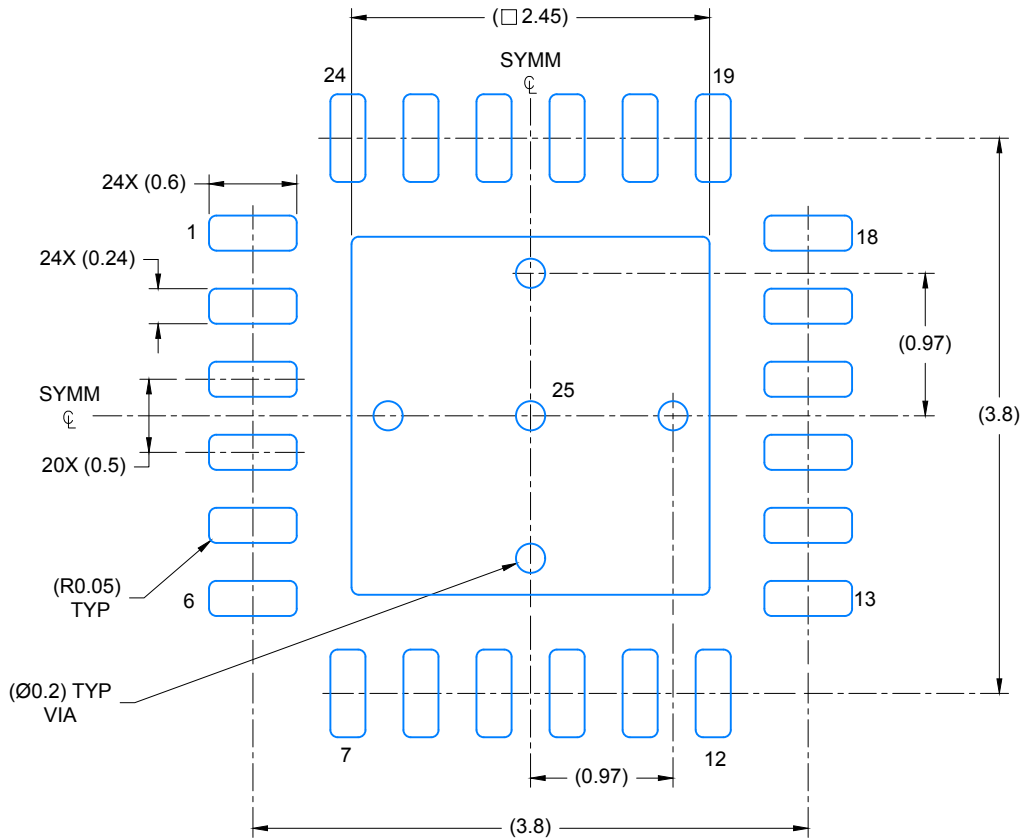
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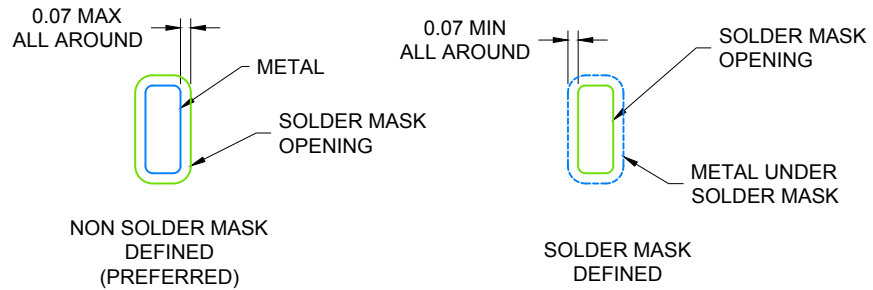
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NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE: 20X

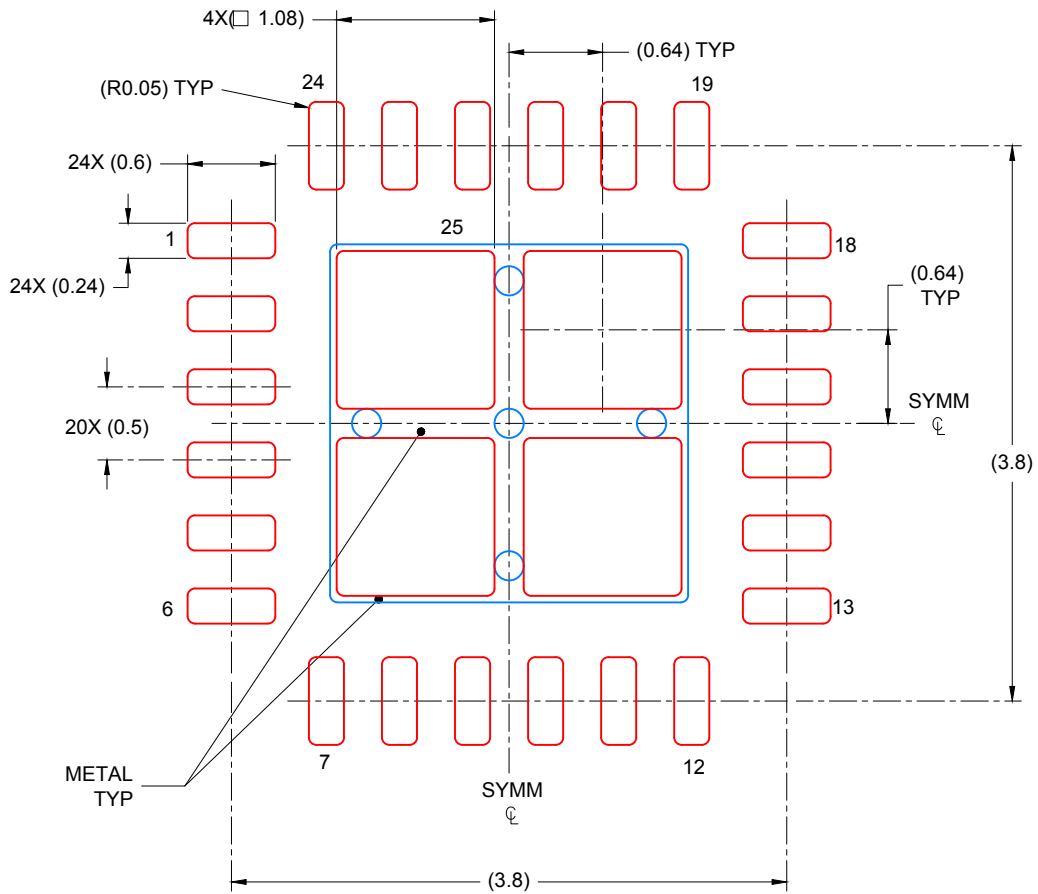


SOLDER MASK DETAILS

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NOTES: (continued)

- For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25:
 78% PRINTED COVERAGE BY AREA UNDER PACKAGE
 SCALE: 20X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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